



**RAYSTAR**

# 曜凌光電股份有限公司

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## RX1602A3-TIW-TS

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### SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:

## Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2012/09/03		First issue
A	2014/11/19		Remove IC information Modify B/L information Correct Contour Drawing.
B	2015/06/26		Modify Backlight Information
C	2016/02/25		Modify Precautions in use of LCD Modules & Static electricity test

# Contents

- 1.General Specification
- 2.Module Classification Information
- 3.Interface Pin Function
- 4.Contour Drawing
- 5.Character Generator ROM Pattern
- 6.Optical Characteristics
- 7.Absolute Maximum Ratings
- 8.Electrical Characteristics
- 9.Backlight Information
- 10.Reliability
- 11.Inspection specification
- 12.Precautions in use of LCD Modules
- 13.Material List of Components for RoHs
- 14.Recommendable Storage

## 1. General Specification

The Features is described as follow:

- Module dimension: 74.2x 25.2 x 6.3 mm
- View area: 61.0 x 15.1 mm
- Active area: 56.2 x 11.5 mm
- Number of Characters: 16 characters x 2 Lines
- Dot size: 0.55 x 0.65 mm
- Dot pitch: 0.60 x 0.70 mm
- Character size: 2.95 x 5.55 mm
- Character pitch: 3.55 x 5.95 mm
- LCD type: FSTN Negative Transmissive
- Duty: 1/16 , 1/5 Bias
- View direction: 6 o'clock
- Backlight Type: LED, White
- IC: ST7032i

## 2.Module Classification Information

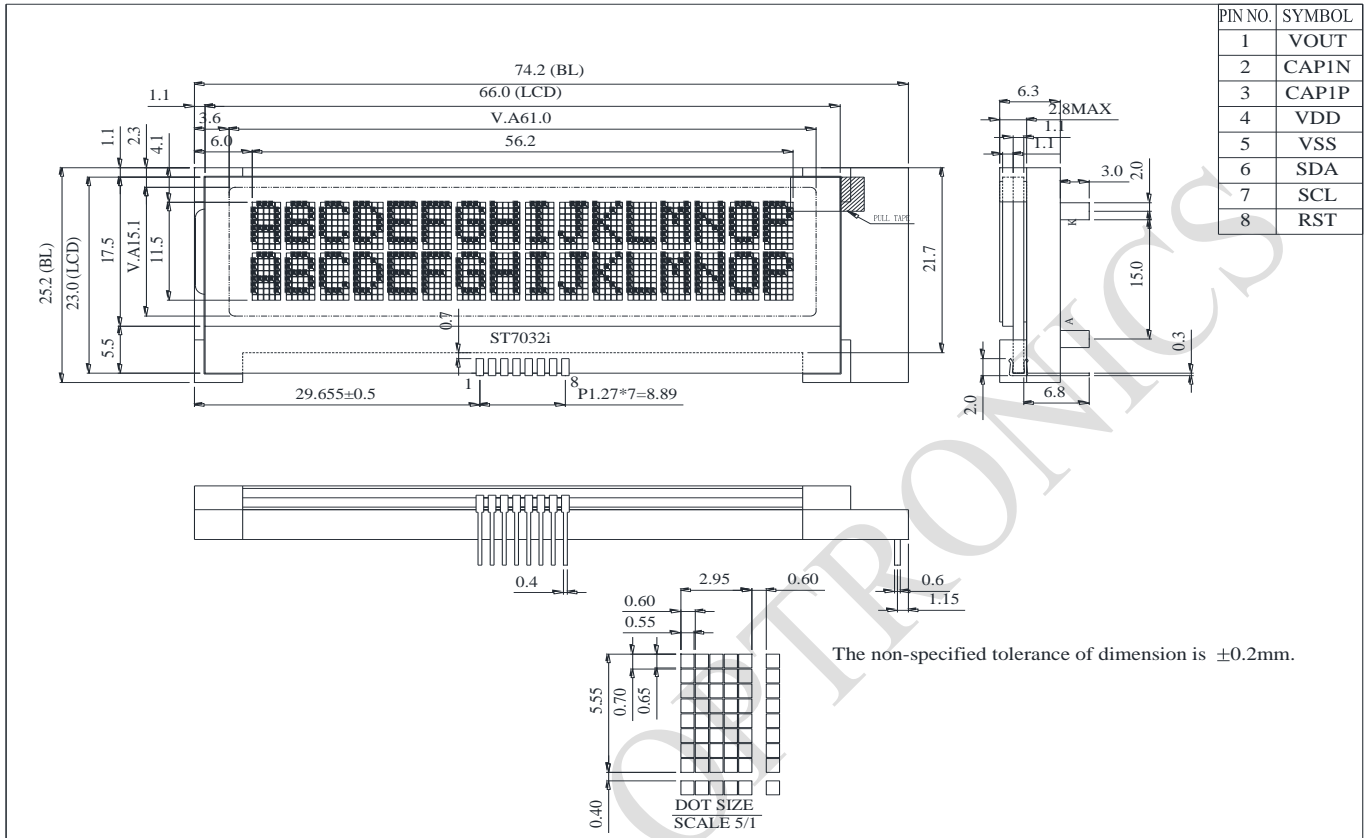
<u>R</u>	<u>X</u>	<u>1602</u>	<u>A3</u>	—	<u>I</u>	<u>I</u>	<u>W</u>	—	<u>TS</u>
①	②	③	④	—	⑤	⑥	⑦	—	⑧

Item	Description			
1	R : Raystar Optronics Inc.			
2	Display	C : Character Type,	T:TAB Type	
		G : Graphic Type	X:COG Type	
3	Number of dots : Character 16 words, 02 Lines.			
4	Serials code :			
5	LCD	P→TN Positive, Gray	V→FSTN Negative, Blue	
		N→TN Negative,	T→FSTN Negative, Black	
		L→VA Negative	D→FSTN Negative (Double film)	
		H→ HTN Positive, Gray	F→FSTN Positive	
		I→HTN Negative, Black	K→FSC Negative	
		U→HTN Negative, Blue	S→FSC Positive	
		B→STN Negative, Blue	E→ISTN Negative, Black	
		G→STN Positive, Gray	C→CSTN Negative, Black	
		Y→STN Positive, Yellow Green	A→ASTN Negative, Black	
6	Polarizer Type, Temperature range, View direction	A : Reflective, N.T, 6:00	K : Transflective, W.T,12:00	
		D : Reflective, N.T, 12:00	1 : Transflective, U.T,6:00	
		G : Reflective, W. T, 6:00	4 : Transflective, U.T.12:00	
		J : Reflective, W. T, 12:00	C : Transmissive, N.T,6:00	
		0 : Reflective, U. T, 6:00	F : Transmissive, N.T,12:00	
		3 : Reflective, U. T, 12:00	I : Transmissive, W. T, 6:00	
		B : Transflective, N.T,6:00	L : Transmissive, W.T,12:00	
		E : Transflective, N.T.12:00	2 : Transmissive, U. T, 6:00	
		H : Transflective, W.T,6:00	5 : Transmissive, U.T,12:00	
7	Backlight	N→ Without backlight	W→LED, White	H→LED, High light White
		P→EL, Blue	A→LED, Amber	S→LED, Full color
		T→EL, Green	R→LED, Red	J→DIP LED, Blue
		D→EL, White	O→LED, Orange	K→DIP LED, White
		M→EL, Yellow Green	B→LED, Blue	E→DIP LED, Yellow
		F→CCFL, White	X→LED, Dual color	L→DIP LED, Amber
		Y→LED, Yellow Green	C→LED, Full color	I→DIP LED, Red
		G→LED, Green		
8	Special code	TS: English and Japanese and European standard font		

### 3.Interface Pin Function

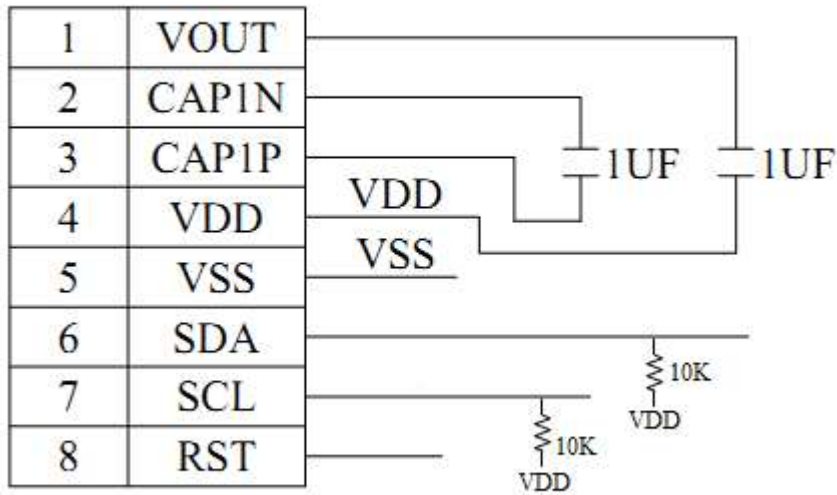
Pin No.	Symbol	Level	Description
1	VOUT		DC/DC voltage converter. Connect a capacitor between this terminal and VIN when the built-in booster is used.
2	CAP1N		For voltage booster circuit(VDD-VSS)
3	CAP1P		External capacitor about 0.1u~4.7uf
4	VDD	3.0/5.0V	Power supply
5	VSS		GND
6	SDA		(In I2C interface DB7 (SDA) is input data. SDA and SCL must connect to I2C bus (I2C bus is to connect a resistor between SDA/SCL and the power of I2C bus ).
7	SCL		(In I2C interface DB6 (SCL) is clock input. SDA and SCL must connect to I2C bus (I2C bus is to connect a resistor between SDA/SCL and the power of I2C bus ).
8	RST		RESET (Low active)

### 4. Contour Drawing

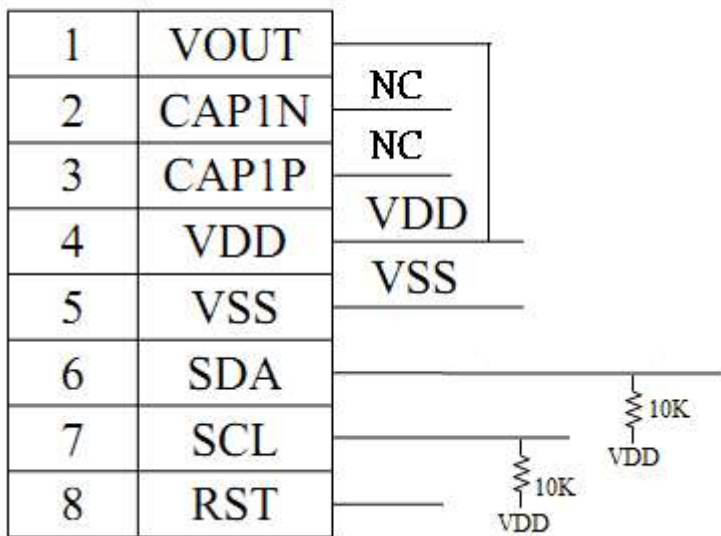


## Application schematic

VDD=3.0V



VDD=5.0V





**INITIALIZE: (3V)**

```
MOV    I2C_CONTROL,#00H ;WRITE COMMAND
MOV    I2C_DATA,#38H    ;Function Set
LCALL  WRITE_CODE
MOV    I2C_CONTROL,#00H ;WRITE COMMAND
MOV    I2C_DATA,#39H    ;Function Set
LCALL  WRITE_CODE
MOV    I2C_DATA,#14H    ;Internal OSC frequency
LCALL  WRITE_CODE
MOV    I2C_DATA,#74H    ;Contrast set
LCALL  WRITE_CODE
MOV    I2C_DATA,#54H    ;Power/ICON control/Contrast set
LCALL  WRITE_CODE
MOV    I2C_DATA,#6FH    ;Follower control
LCALL  WRITE_CODE
MOV    I2C_DATA,#0CH    ;Display ON/OFF
LCALL  WRITE_CODE
MOV    I2C_DATA,#01H    ;Clear Display
LCALL  WRITE_CODE
```

**INITIALIZE: (5V)**

```
MOV     I2C_CONTROL,#00H;WRITE COMMAND
MOV     I2C_DATA,#38H      ;Function Set
LCALL   WRITE_CODE
MOV     I2C_CONTROL,#00H;WRITE COMMAND
MOV     I2C_DATA,#39H      ;Function Set
LCALL   WRITE_CODE
MOV     I2C_DATA,#14H      ;Internal OSC frequency
LCALL   WRITE_CODE
MOV     I2C_DATA,#79H      ;Contrast set
LCALL   WRITE_CODE
MOV     I2C_DATA,#50H      ;Power/ICON control/Contrast set
LCALL   WRITE_CODE
MOV     I2C_DATA,#6CH      ;Follower control
LCALL   WRITE_CODE
MOV     I2C_DATA,#0CH      ;Display ON/OFF
LCALL   WRITE_CODE
MOV     I2C_DATA,#01H      ;Clear Display
LCALL   WRITE_CODE
```

## 5.Character Generator ROM Pattern

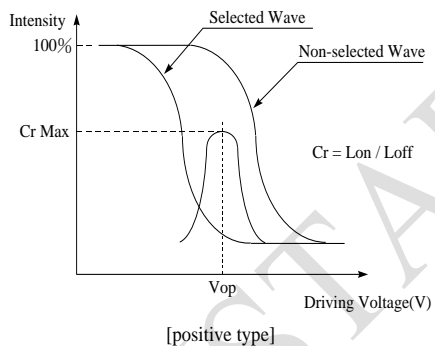
### ST7032-3J

b7-b4 b3-b0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)	A	0	P	F	B	E	W	4	.	2	8				
0001	(2)	A	!	1	A	Q	a	9	N	A	7	8	W	.	U	8
0010	(3)	A	"	2	B	R	b	r	0	A	E	6	6	U	W	8
0011	(4)	A	#	3	O	S	c	s	0	A	R	E	W	U	2	4
0100	(5)	A	\$	4	D	T	d	t	0	A	B	r	6	7	φ	8
0101	(6)	A	%	5	E	U	e	u	0	A	N	e	a	x	U	7
0110	(7)	A	&	6	F	V	f	v	0	A	N	e	W	7	W	8
0111	(8)	Q	'	7	G	W	g	w	x	0	L	3	a	I	'	E
1000	(1)	E	(	8	H	X	h	x	0	E	π	W	0	U		8
1001	(2)	E	)	9	I	Y	i	y	0	E	7	W	0	↑		8
1010	(3)	E	*	:	J	Z	j	z	0	E	0	K	0	↓	E	8
1011	(4)	E	+	;	K	C	k	c	0	E	4	a	"	W	0	8
1100	(5)	I	,	<	L	φ	l	φ	0	I	W	M	N	N	U	8
1101	(6)	I	-	=	M	I	m	i	Y	i	b	H	2	M	#	8
1110	(7)	I	.	>	N	^	n	^	b	i	W	m	f	7	0	8
1111	(8)	I	/	?	O	_	o	_	0	I	3	T	E	.	0	8

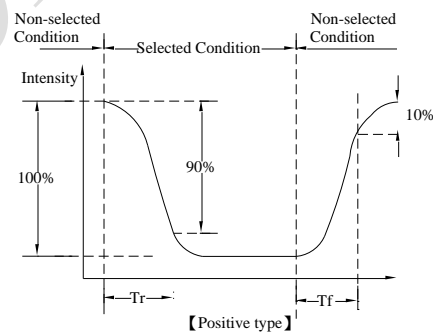
## 6. Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	$\theta$	$CR \geq 2$	0	—	30	$\psi = 180^\circ$
	$\theta$	$CR \geq 2$	0	—	60	$\psi = 0^\circ$
	$\theta$	$CR \geq 2$	0	—	45	$\psi = 90^\circ$
	$\theta$	$CR \geq 2$	0	—	45	$\psi = 270^\circ$
Contrast Ratio	CR	—	—	5	—	—
Response Time	T rise	—	—	150	200	ms
	T fall	—	—	150	200	ms

### Definition of Operation Voltage (Vop)



### Definition of Response Time (Tr, Tf)



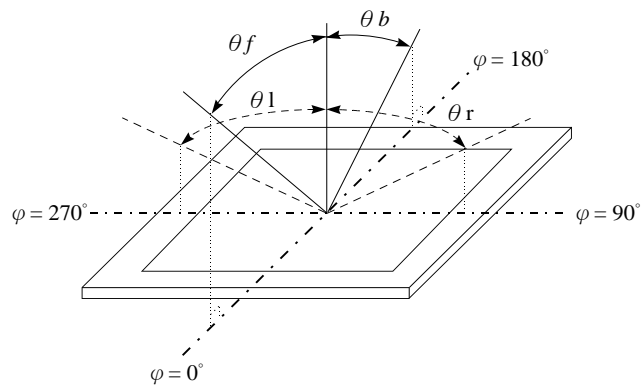
### Conditions :

Operating Voltage : Vop

Viewing Angle( $\theta$ ,  $\varphi$ ) :  $0^\circ$ ,  $0^\circ$

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

### Definition of viewing angle( $CR \geq 2$ )



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## 7. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	$T_{OP}$	-20	—	+70	°C
Storage Temperature	$T_{ST}$	-30	—	+80	°C
Input Voltage	$V_{IN}$	-0.3	—	$V_{DD}+0.3$	V
Power Supply Voltage	$V_{DD}-V_{SS}$	-0.3	—	+6.0	V
LCD Driver Voltage	$V_{LCD}$	2.7	—	7.0	V

## 8. Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD-VSS}$	—	3	3.3	5 (bon=1 max=3.5V)	V
Supply Voltage For LCD	$V_{LCD}$	Ta=-20°C	—	—	—	V
		Ta=25°C	—	4.5	—	V
		Ta=70°C	—	—	—	V
Input High Volt.	$V_{IH}$	—	0.7 $V_{DD}$	—	$V_{DD}$	V
Input Low Volt.	$V_{IL}$	—	—	—	0.2 $V_{DD}$	V
Output High Volt.	$V_{OH}$	—	0.8 $V_{DD}$	—	$V_{DD}$	V
Output Low Volt.	$V_{OL}$	—	—	—	0.2 $V_{DD}$	V
Supply Current(No include LED Backlight)	$I_{DD}$	—	—	0.19		mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

## 9.Backlight Information

### Specification

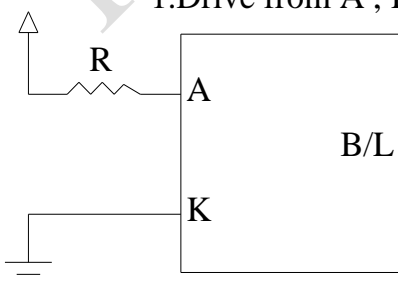
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	I <sub>LED</sub>	—	32	40	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	—
Reverse Voltage	V <sub>R</sub>	—	—	5	V	—
Range	X	0.27	0.29	0.31		I <sub>LED</sub> =32mA
	Y	0.28	0.30	0.32		
Luminance (Without LCD)	I <sub>V</sub>	616	770	—	CD/M <sup>2</sup>	I <sub>LED</sub> =32mA
LED Life Time (For Reference only)	—	—	50K	—	Hr.	I <sub>LED</sub> =32mA 25°C,50-60%RH, (Note 1)
Color	White					

**Note:** The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

**Note 1:**50K hours is only an estimate for reference.


LED B\L Drive Method

1.Drive from A , K





## 10. Reliability

Environmental Test			
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	—
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C    25°C    70°C  1 cycle	-20°C/70°C 10 cycles	—
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times	—

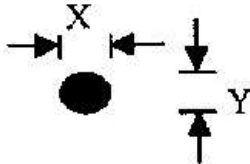
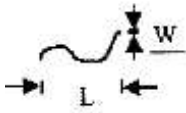
### Content of Reliability Test (Wide temperature, -20°C~70°C)

**Note1:** No dew condensation to be observed.

**Note2:** The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

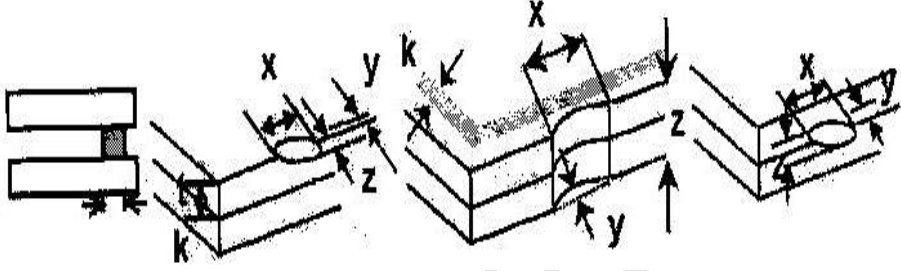
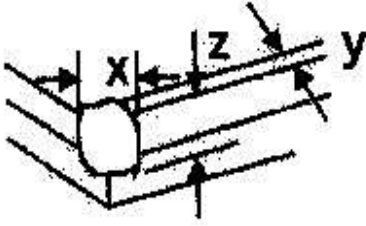
**Note3:** The packing have to including into the vibration testing.

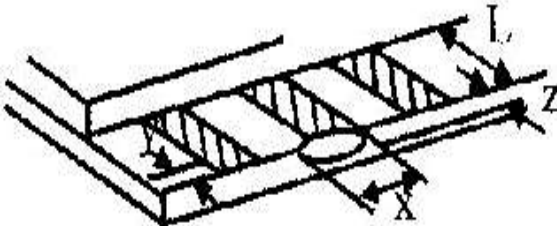
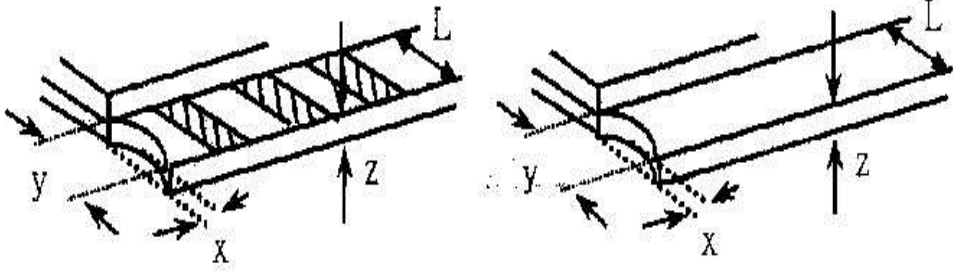
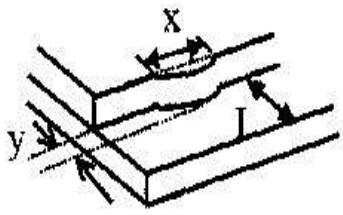
# 11. Inspection specification

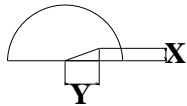
NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$ , no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y) / 2$  <table border="1" data-bbox="821 1041 1348 1294"> <thead> <tr> <th>SIZE</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.10</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.10 &lt; \Phi \leq 0.20</math></td> <td>2</td> </tr> <tr> <td><math>0.20 &lt; \Phi \leq 0.25</math></td> <td>1</td> </tr> <tr> <td><math>0.25 &lt; \Phi</math></td> <td>0</td> </tr> </tbody> </table>	SIZE	Acceptable Q TY	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	1	$0.25 < \Phi$	0	2.5		
		SIZE	Acceptable Q TY												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	1														
$0.25 < \Phi$	0														
3.2 Line type : (As following drawing)  <table border="1" data-bbox="715 1541 1348 1792"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>---</td> <td><math>W \leq 0.02</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>L \leq 3.0</math></td> <td><math>0.02 &lt; W \leq 0.03</math></td> <td rowspan="2">2</td> </tr> <tr> <td><math>L \leq 2.5</math></td> <td><math>0.03 &lt; W \leq 0.05</math></td> </tr> <tr> <td>---</td> <td><math>0.05 &lt; W</math></td> <td>As round type</td> </tr> </tbody> </table>	Length	Width	Acceptable Q TY	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.03$	2	$L \leq 2.5$	$0.03 < W \leq 0.05$	---	$0.05 < W$	As round type	2.5
Length	Width	Acceptable Q TY													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.03$	2													
$L \leq 2.5$	$0.03 < W \leq 0.05$														
---	$0.05 < W$	As round type													

04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size $\Phi$	Acceptable Q TY	2.5
			$\Phi \leq 0.20$	Accept no dense	
			$0.20 < \Phi \leq 0.50$	3	
			$0.50 < \Phi \leq 1.00$	2	
			$1.00 < \Phi$	0	
			Total Q TY	3	

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NO	Item	Criterion	AQL																		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination																			
06	Chipped glass	<p>Symbols Define:            x: Chip length      y: Chip width      z: Chip thickness            k: Seal width      t: Glass thickness      a: LCD side length            L: Electrode pad length:</p> <p>6.1 General glass chip :            6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="459 981 1369 1191"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td><math>Z \leq 1/2t</math></td> <td>Not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> <tr> <td><math>1/2t &lt; z \leq 2t</math></td> <td>Not exceed 1/3k</td> <td><math>x \leq 1/8a</math></td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is total length of each chip.</p> <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="459 1624 1369 1834"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td><math>Z \leq 1/2t</math></td> <td>Not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> <tr> <td><math>1/2t &lt; z \leq 2t</math></td> <td>Not exceed 1/3k</td> <td><math>x \leq 1/8a</math></td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is the total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			

NO	Item	Criterion	AQL																
06	Glass crack	<p>Symbols :</p> <p>x: Chip length      y: Chip width      z: Chip thickness</p> <p>k: Seal width      t: Glass thickness      a: LCD side length</p> <p>L: Electrode pad length</p> <p>6.2 Protrusion over terminal :</p> <p>6.2.1 Chip on electrode pad :</p>  <table border="1" data-bbox="379 862 1300 958"> <thead> <tr> <th>y: Chip width</th> <th>x: Chip length</th> <th>z: Chip thickness</th> </tr> </thead> <tbody> <tr> <td><math>y \leq 0.5\text{mm}</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </tbody> </table> <p>6.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="450 1344 1276 1456"> <thead> <tr> <th>y: Chip width</th> <th>x: Chip length</th> <th>z: Chip thickness</th> </tr> </thead> <tbody> <tr> <td><math>y \leq L</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </tbody> </table> <p>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</p> <p>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</p> <p>6.2.3 Substrate protuberance and internal crack.</p>  <table border="1" data-bbox="790 1758 1348 1859"> <thead> <tr> <th>y: width</th> <th>x: length</th> </tr> </thead> <tbody> <tr> <td><math>y \leq 1/3L</math></td> <td><math>x \leq a</math></td> </tr> </tbody> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$x \leq a$	2.5
		y: Chip width	x: Chip length	z: Chip thickness															
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$x \leq a$																		

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  $X * Y \leq 2\text{mm}^2$	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

## 12. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.



### 13. Material List of Components for RoHs

1. RAYSTAR Optronics. Inc. hereby declares that all of or part of products (with the mark “#”in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2.Process for RoHS requirement : (only for RoHS inspection)

(1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C ;

Recommended customer’s soldering temp. of connector : 280°C, 3 seconds.

## 14.Recommendable Storage

1. Place the panel or module in the temperature  $25^{\circ}\text{C}\pm 5^{\circ}\text{C}$  and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module.

RAYSTAR OPTRONICS

**LCM Sample Estimate Feedback Sheet**

**Module Number :** \_\_\_\_\_

**1 、 Panel Specification :**

1. Panel Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. View Direction :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Numbers of Dots :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. View Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Active Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Operating Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Storage Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Others :	_____	

**2 、 Mechanical Specification :**

1. PCB Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Frame Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Material of Frame :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Connector Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Fix Hole Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Backlight Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Thickness of PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Height of Frame to PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9. Height of Module :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
10. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

**3 、 Relative Hole Size :**

1. Pitch of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Hole size of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Mounting Hole size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Mounting Hole Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

**4 、 Backlight Specification :**

1. B/L Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. B/L Color :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. B/L Driving Voltage (Reference for LED Type) :	<input type="checkbox"/> Pass <input type="checkbox"/> NG , _____	
4. B/L Driving Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Brightness of B/L :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. B/L Solder Method :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

Module Number : \_\_\_\_\_

**5 · Electronic Characteristics of Module :**

1.Input Voltage :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2.Supply Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3.Driving Voltage for LCD :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4.Contrast for LCD :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5.B/L Driving Method :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6.Negative Voltage Output :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7.Interface Function :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8.LCD Uniformity :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9.ESD test :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
10.Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

**6 · Summary :**

Sales signature : \_\_\_\_\_

Customer Signature : \_\_\_\_\_

Date : / /